

L Number	Hits	Search Text	DB	Time stamp
1	4162	barrier\$1 near10 (sensor\$1 or detector\$1 or semiconductor\$1 or CCD\$1) and (packag\$3 or assembl\$3 or hous\$3 or manufactur\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:51
2	574	barrier\$1 near10 (top\$1 or surface\$1 or face\$3) near10 (sensor\$1 or detector\$1 or semiconductor\$1 or CCD\$1) and (packag\$3 or assembl\$3 or hous\$3 or manufactur\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:01
3	290	encapsulat\$3 near10 (sensor\$1 or detector\$1 or semiconductor\$1 or CCD\$1) same (substrate\$1) and (packag\$3 or assembl\$3 or hous\$3 or manufactur\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:02
4	0	rasin\$1 same (bleed\$3 or leak\$3) and (encapsulat\$3 near10 (sensor\$1 or detector\$1 or semiconductor\$1 or CCD\$1) same (substrate\$1) and (packag\$3 or assembl\$3 or hous\$3 or manufactur\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:03
5	2	resin\$1 same (bleed\$3 or leak\$3) and (encapsulat\$3 near10 (sensor\$1 or detector\$1 or semiconductor\$1 or CCD\$1) same (substrate\$1) and (packag\$3 or assembl\$3 or hous\$3 or manufactur\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:04
6	14	resin\$1 same (bleed\$3 or leak\$3) and (barrier\$1 near10 (sensor\$1 or detector\$1 or semiconductor\$1 or CCD\$1) and (packag\$3 or assembl\$3 or hous\$3 or manufactur\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:05
7	1844	resin\$1 same (bleed\$3 or leak\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:14
8	1	(resin\$1 same (bleed\$3 or leak\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and (encapsulat\$3 near10 (sensor\$1 or detector\$1 or semiconductor\$1 or CCD\$1) same (substrate\$1) and (packag\$3 or assembl\$3 or hous\$3 or manufactur\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:07
9	7	(resin\$1 same (bleed\$3 or leak\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and (barrier\$1 near10 (sensor\$1 or detector\$1 or semiconductor\$1 or CCD\$1) and (packag\$3 or assembl\$3 or hous\$3 or manufactur\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:07
10	64	(resin\$1 same (bleed\$3 or leak\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and (image\$1 or picture\$1) same (sensor\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:16
11	700	(resin\$1 same (bleed\$3 or leak\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:19
12	19	(resin\$1 same (bleed\$3 or leak\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and 257/\$.ccls. and (image\$1 or picture\$1) and (camera\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:19
13	5	(resin\$1 same (bleed\$3 or leak\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and (image\$1 or picture\$1) same (sensor\$1) and barrier\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:14

14	519	resin\$1 near10 (bleed\$3 or leak\$3) same (block\$3 or barrier\$1 or stop\$3 or prevent\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:16
15	16	(resin\$1 near10 (bleed\$3 or leak\$3) same (block\$3 or barrier\$1 or stop\$3 or prevent\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and (image\$1 or picture\$1) same (sensor\$1 or camera\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:16
16	266	(resin\$1 near10 (bleed\$3 or leak\$3) same (block\$3 or barrier\$1 or stop\$3 or prevent\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:41
17	7	(resin\$1 near10 (bleed\$3 or leak\$3) same (block\$3 or barrier\$1 or stop\$3 or prevent\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and 257/\$.ccls. and (image\$1 or picture\$1) and (camera\$1 or sensor\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:23
18	2	(resin\$1 near10 (bleed\$3 or leak\$3) same (block\$3 or barrier\$1 or stop\$3 or prevent\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and 250/\$.ccls. and (image\$1 or picture\$1) and (camera\$1 or sensor\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:24
19	10	((("5818094") or ("5218234") or ("5433911") or ("4871921") or ("5923958"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:24
20	11	("4001863" "4302674" "4410927" "4720424" "4745470" "4961106" "5239412" "5244707" "5391915" "5523608" "5583376").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:26
21	2	5818094.URPN.	USPAT	2004/03/22 15:28
22	1	(resin\$1 near10 (bleed\$3 or leak\$3) same (block\$3 or barrier\$1 or stop\$3 or prevent\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and 250/208.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:30
23	1	(resin\$1 near10 (bleed\$3 or leak\$3) same (block\$3 or barrier\$1 or stop\$3 or prevent\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and 257/434.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:30
24	5	(resin\$1 near10 (bleed\$3 or leak\$3) same (block\$3 or barrier\$1 or stop\$3 or prevent\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and 257/43\$1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 16:07
25	19	(resin\$1 near10 (bleed\$3 or leak\$3) same (block\$3 or barrier\$1 or stop\$3 or prevent\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and 257/68\$1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:31
26	269158	(resin\$1 near10 (bleed\$3 or leak\$3) same (block\$3 or barrier\$1 or stop\$3 or prevent\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and 257/\$.ccls. (image\$1 or picture\$1 or camera\$1) and (sensor\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:43

27	2	(resin\$1 near10 (bleed\$3 or leak\$3) same (block\$3 or barrier\$1 or stop\$3 or prevent\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and 257/\$.ccls. and(image\$1 or picture\$1 or camera\$1) and (sensor\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:45
28	32	(resin\$1 near10 (bleed\$3 or leak\$3) same (block\$3 or barrier\$1 or stop\$3 or prevent\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and 257/\$.ccls. and(image\$1 or picture\$1 or camera\$1 or sensor\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:50
29	16	(resin\$1 near10 (bleed\$3 or leak\$3) same (block\$3 or barrier\$1 or stop\$3 or prevent\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and 264/\$.ccls. and(image\$1 or picture\$1 or camera\$1 or sensor\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:50
30	3	(resin\$1 near10 (bleed\$3 or leak\$3) same (block\$3 or barrier\$1 or stop\$3 or prevent\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and 250/\$.ccls. and(image\$1 or picture\$1 or camera\$1 or sensor\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:51
31	2	(resin\$1 near10 (bleed\$3 or leak\$3) same (block\$3 or barrier\$1 or stop\$3 or prevent\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and 348/\$.ccls. and(image\$1 or picture\$1 or camera\$1 or sensor\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:53
32	60	resin\$1 near5 (stop\$3 or block\$3 or barrier\$1) near10 (sensor\$1 or detector\$1 or semiconductor\$1 or CCD\$1) and (packag\$3 or assembl\$3 or hous\$3 or manufactur\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:54
33	8	(resin\$1 near10 (bleed\$3 or leak\$3) same (block\$3 or barrier\$1 or stop\$3 or prevent\$3) and (sensor\$1 or CCD or semiconductor\$1) same (chip\$1 or packag\$3 or hous\$3 or assembl\$3)) and 438/\$.ccls. and(image\$1 or picture\$1 or camera\$1 or sensor\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 15:54
34	110	resin\$1 near5 (stop\$3 or block\$3 or barrier\$1) near10 (sensor\$1 or detector\$1 or semiconductor\$1 or CCD\$1) and (packag\$3 or assembl\$3 or hous\$3 or manufactur\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 16:07
35	586	348/373.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 16:07
36	206	348/374.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 16:07
37	283	348/375.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 16:07
38	572	348/207.99.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 16:07

39	565	257/434.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/22 16:07
40	934	257/435.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/22 16:07
41	625	257/632.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/22 16:07
42	597	257/680.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/22 16:08
43	2135	250/208.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/22 16:08